



Product Change Notification **CN-202109019F**

Issue date: 08 Oct 2021
Effective date: 20 Jan 2022

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Change of back side metallization thickness and introduction of new EMCs and Cu wire for a few products in SOT23

Change Category

<input checked="" type="checkbox"/>	<input type="checkbox"/>				
Wafer	Assembl				
Fab					
Process	y				
<input type="checkbox"/>	Process	<input type="checkbox"/>	Product Marking	<input type="checkbox"/>	Test Design
Wafer	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Mechanical	<input type="checkbox"/>	Location Errata
Fab	Assembl		Specification	<input type="checkbox"/>	Test Process
Material	y	<input type="checkbox"/>		<input type="checkbox"/>	Test Process
s	Materials		Packing/Shipping/Labelin	<input type="checkbox"/>	Test Equipment
<input type="checkbox"/>	<input type="checkbox"/>		g		Equipment coverage
Wafer	Assembl				
Fab	y				
Location	Location				

Details of this change

The back side metallization thickness will be changed from 2.15 µm to 1.75 µm.

The change of the back side metallization thickness is combined with the introduction of additional EMCs (epoxy mold compounds) GR646CHN, CV4112B and E500HK.

Following the details:

Current Products

- back side metallization thickness 2.15 µm
- epoxy mold compound: GR646, 3400FPG (where affected)

Changed Products

- back side metallization thickness 1.75 µm
- epoxy mold compound: GR646, CV4112B, E500HK and GR646CHN (where affected)

SQR_202109019F.pdf: https://qcm.nexperia.com/Document/DOC-520070/SQR_202109019F.pdf

202109019F_PCN-FORM-Rev_4_0.xlsm:
https://qcm.nexperia.com/Document/DOC-520051/202109019F_PCN-FORM-Rev_4_0.xlsm

202109019F_PCN-Delta-Qualification-Matrix-ZVEI-4_1.xlsm:
https://qcm.nexperia.com/Document/DOC-520050/202109019F_PCN-Delta-Qualification-Matrix-ZVEI-4_1.xlsm

Why do we implement this change?

- to increase efficiency of volume production
- to increase flexibility and volume ramp-up

Identification of affected products

Changed product can be identified by date code after implementation.

Product availability

Production

Planned first shipment: 01 Feb 2022

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 07 Nov 2021. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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<u>SalesItem_name</u>	<u>Affected Part Numbers</u>
934062304215	2PB710ASL,215
934062304235	2PB710ASL,235
934062315215	2PD602ASL,215
934062315235	2PD602ASL,235
934051280215	BAT720,215
934051280235	BAT720,235
934058979215	PDTB113ZT,215